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FORM HDP-1449 (Based on Form PTO-1449) PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)		ATTORNEY DOCKET No. 6550-000013/COA	SERIAL No. 10/730,398
<div style="display: flex; align-items: center;"> <div style="border: 1px solid black; border-radius: 50%; padding: 10px; margin-right: 10px; text-align: center;"> DEC 12 2006 PATENT & TRADEMARK OFFICE </div> <div> Sheet 1 of 3 </div> </div>		APPLICANT Biehler, et al.	
		FILING DATE 12/8/2003	GROUP 1742

U.S. PATENT DOCUMENTS						
Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.	✓	3,481,795*	12/1969	Lane		
2.		4,248,905*	02/1981	Harvey		
3.		4,358,884*	11/1982	Harvey et al.		
4.		4,506,822*	3/1985	Hammersand et al.		
5.		5,066,544*	11/1991	Betrabet et al.		
6.		5,094,700*	3/1992	Sekhar		
7.		5,344,607*	9/1994	Gonya et al.		
8.		5,429,689*	7/1995	Shangguan et al.		
9.	✓	5,527,628*	6/1996	Anderson et al.		

* Previously submitted in an IDS in parent application.

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)		
Ref. Desig.	Examiner's Initials	
1.	✓	Anderson, et al., "Microstructural Modifications and Properties of Sn-Ag-Cu Solder Joints Induced By Alloying", Journal of Electronic Materials, vol. 31, no. 11, pp. 1166-1174 (2002)
2.	✓	Attarwala, A.I. et al., "Confirmation of Creep and Fatigue Damage in Pb/Sn Solder Joints," J. Electron. Packag. 114:109-111 (1992)*
3.	✓	Betrabet, H.S. et al., "Processing Dispersion-Strengthened Sn-Pb Solders To Achieve Microstructural Refinement And Stability," Script Metall. 25:2323-2328 (1991)*
4.	✓	Betrabet, H.S. et al., "Towards Increased Fatigue Resistance In Sn-Pb Solders By Dispersion Strengthening," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1276-1277 (1992)*
5.	✓	Clough, R.B. et al., "Preparation And Properties Of Reflowed Paste And Bulk Composite Solder," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1256-1265 (1992)*
6.	✓	Frear, D.R. et al., "Thermal Fatigue In Solder Joints," JOM, pgs. 18-22 (June, 1988)*

Examiner: <u>S. Iq</u>	Date Considered: <u>3/5/07</u>
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